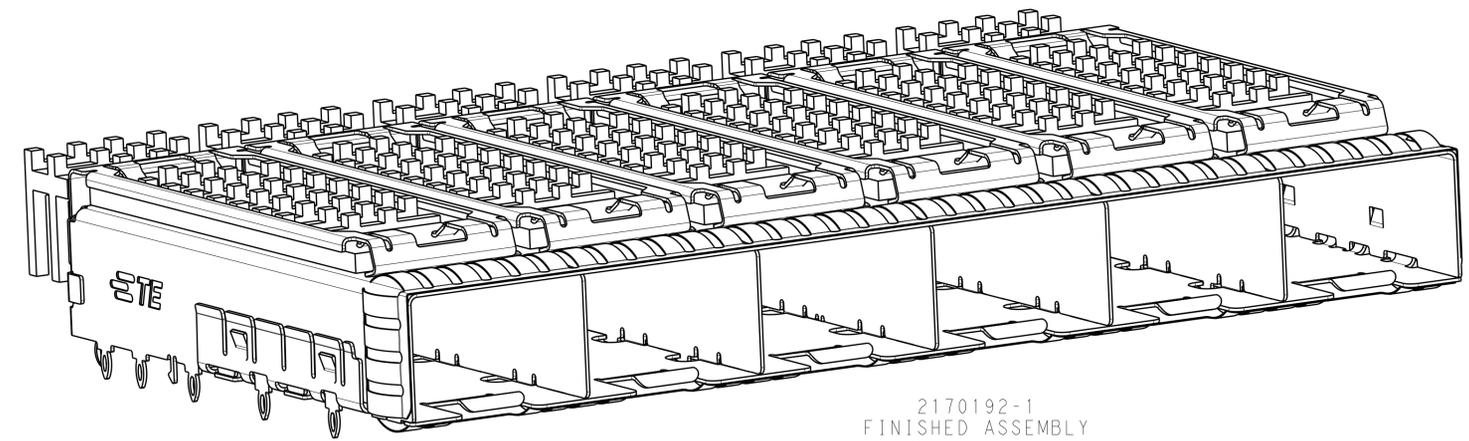
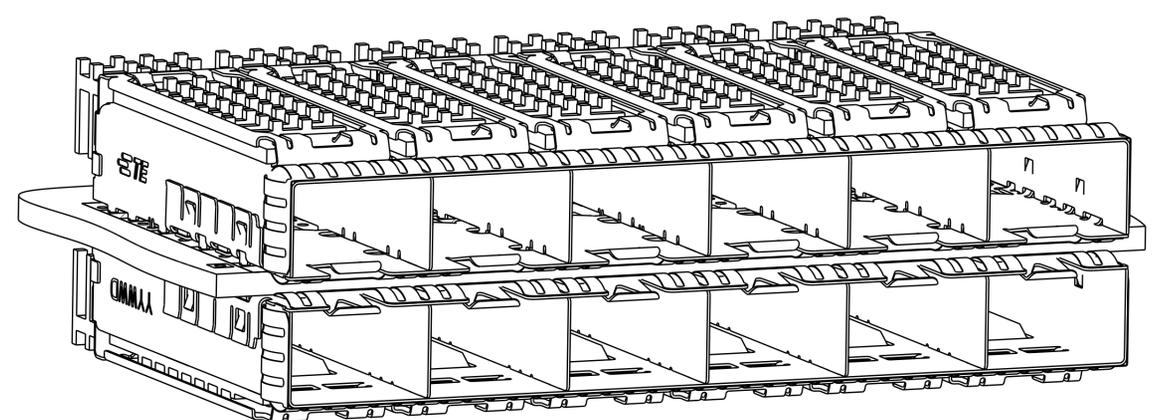
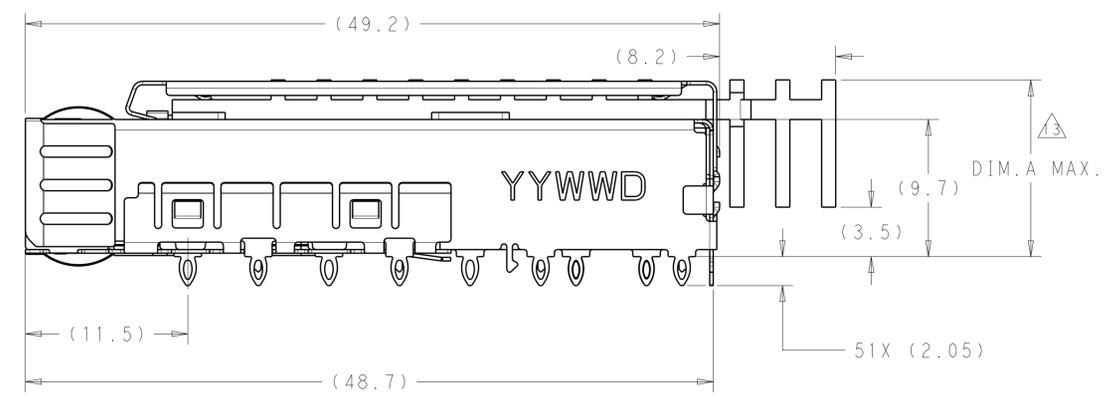
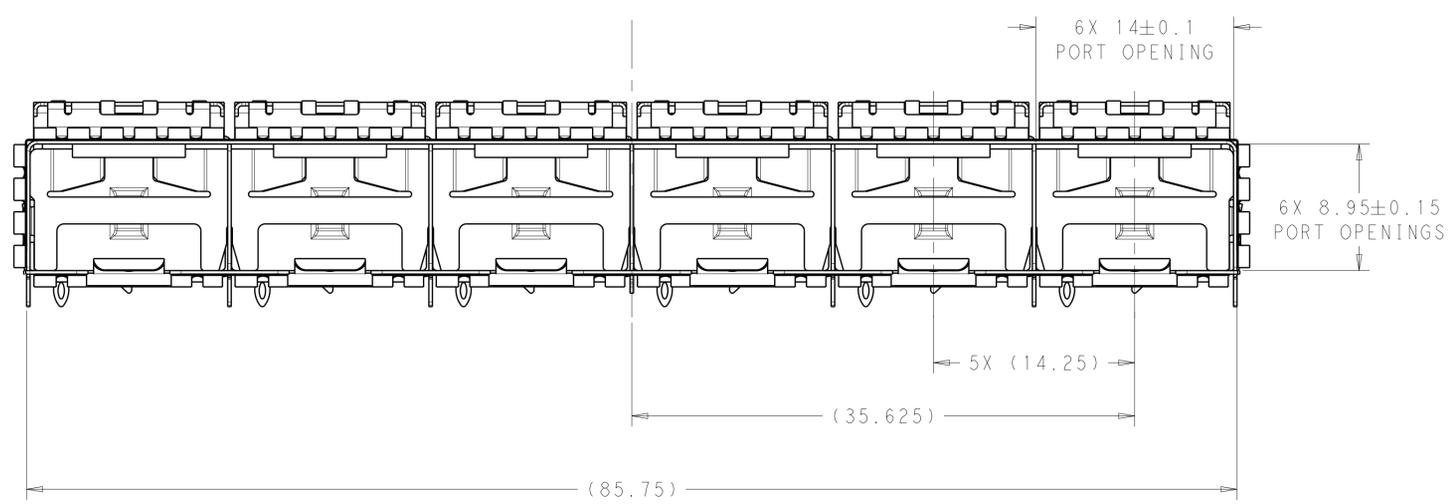


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2170192-1
FINISHED ASSEMBLY
SCALE 4:1

- 1 MATERIAL:
CAGE ASSEMBLY: 0.25mm THICK NICKEL SILVER ALLOY.
HEATSINK CLIP: STAINLESS STEEL
HEATSINK: ALUMINUM
- 2 FINISH:
SPRINGS: MINIMUM OF 0.8um TIN PLATE OVER A MINIMUM OF 0.8um NICKEL UNDERPLATE. NON-PLATED EDGES PERMISSIBLE.
HEATSINK CLIP: PASSIVATE
2170192-1/-2 HEATSINK: HARD ANODIC COATING
2170192-3 HEATSINK: BLACK ANODIZE
- 3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 4 PADS AND VIAS CHASSIS GROUND.
- 5. INTERPRETATION OF DATUM REFERENCE FRAME IN ACCORDANCE WITH SECT 4.4.1.1 OF ASME Y14.5M-1994.
- 6 MINIMUM PCB BOARD THICKNESS:
SINGLE SIDED = 1.50
DOUBLE SIDED = 2.25
- 7 HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 14.25mm.
- 8 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 9 REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 10 REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 11. CERTAIN MATING TRANSCEIVERS MAY REQUIRE ADDITIONAL PCB THICKNESS THAT WOULD BE DETERMINED BY THE CUSTOMER.
- 12. PRODUCT COMPLIES WITH SPECIFICATION SFF-8433 IMPROVED PLUGGABLE FORM FACTOR FOR SFP+ GANGED CAGES.
- 13 DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE



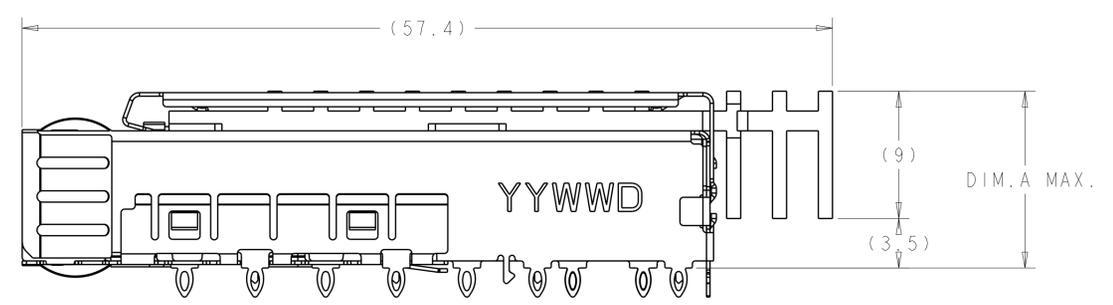
2170192-1
MOUNTED BELLY TO BELLY ON PCB
SCALE 3:1

PRELIMINARY	13.10 MAX.(WORKING)	FIN TYPE	HEAT SINK W/ THE FIRST ROW PIN	2170192-3
	20.2 MAX	PIN TYPE	HEAT SINK W/ THE FIRST ROW PIN	2170192-2
	13 MAX	PIN TYPE	HEAT SINK W/O THE FIRST ROW PIN	2170192-1
	A	HEAT SINK	DESCRIPTION	PART NUMBER

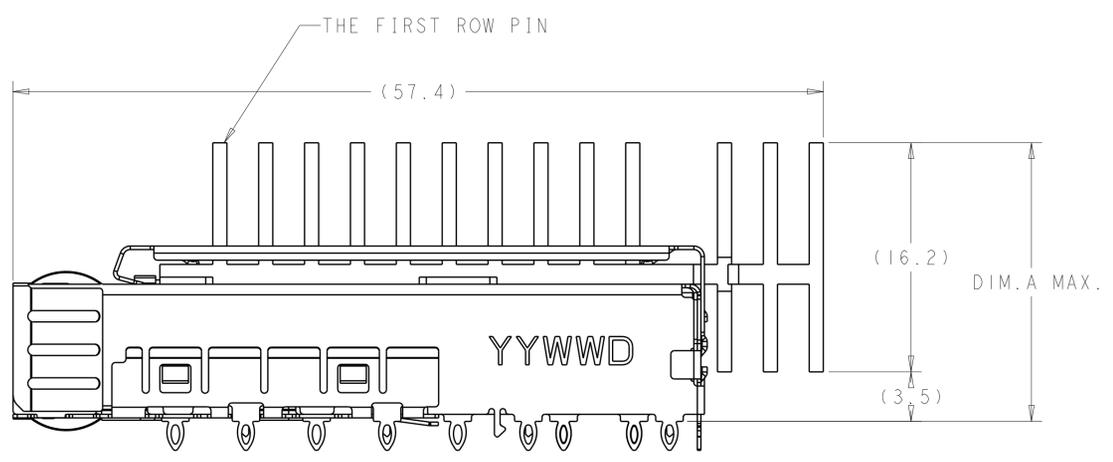
THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	OWN: TIM XUE 22NOV2011	STE TE Connectivity
mm	0 PLC ±0.25	CHK: ALEX CAI 22NOV2011	
	1 PLC ±0.20	APPV: ALEX CAI 22NOV2011	
	2 PLC ±0.15	PRODUCT SPEC: 108-2364	
	3 PLC ±0.1	APPLICATION SPEC: 114-13120	NAME: SFP+ ENHANCED 1X6 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK
	4 PLC ±0.1	ANGLES ±1°	SIZE: CAGE CODE DRAWING NO. RESTRICTED TO
MATERIAL	FINISH	WEIGHT	A100779C=2170192
		Customer Drawing	SCALE 4:1 SHEET 1 OF 5 REV A

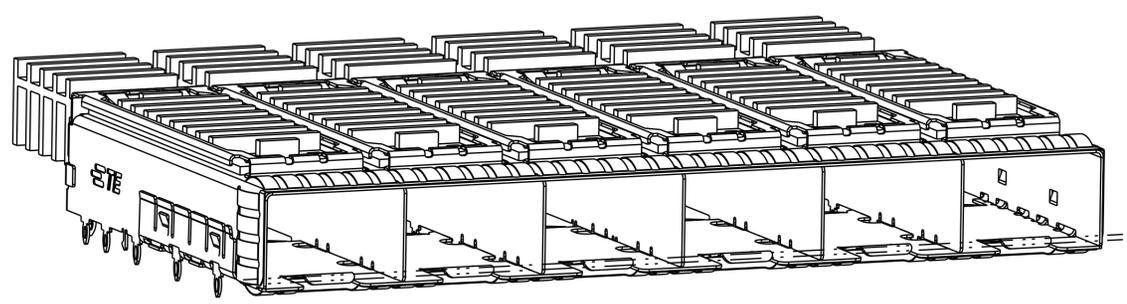
LOC	DIST	REVISIONS					
GP	00	P	LTN	DESCRIPTION	DATE	DMN	APVD
-	-	-	-	SEE SHEET 1	-	-	-



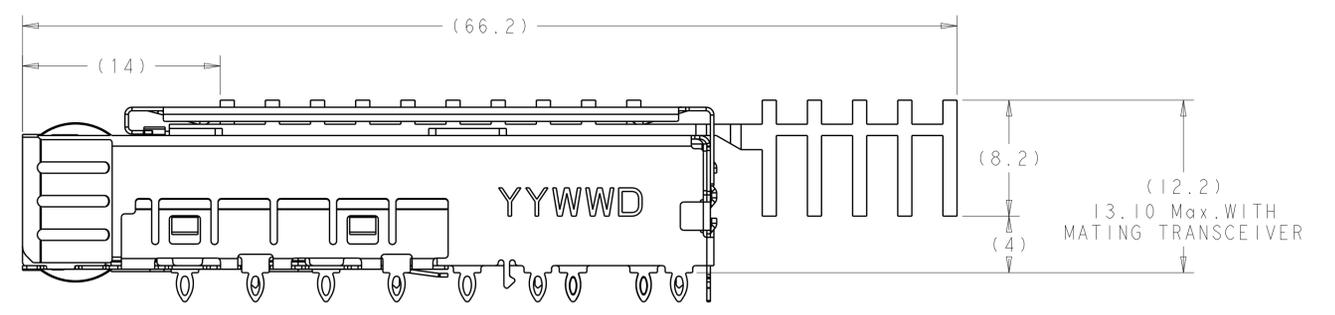
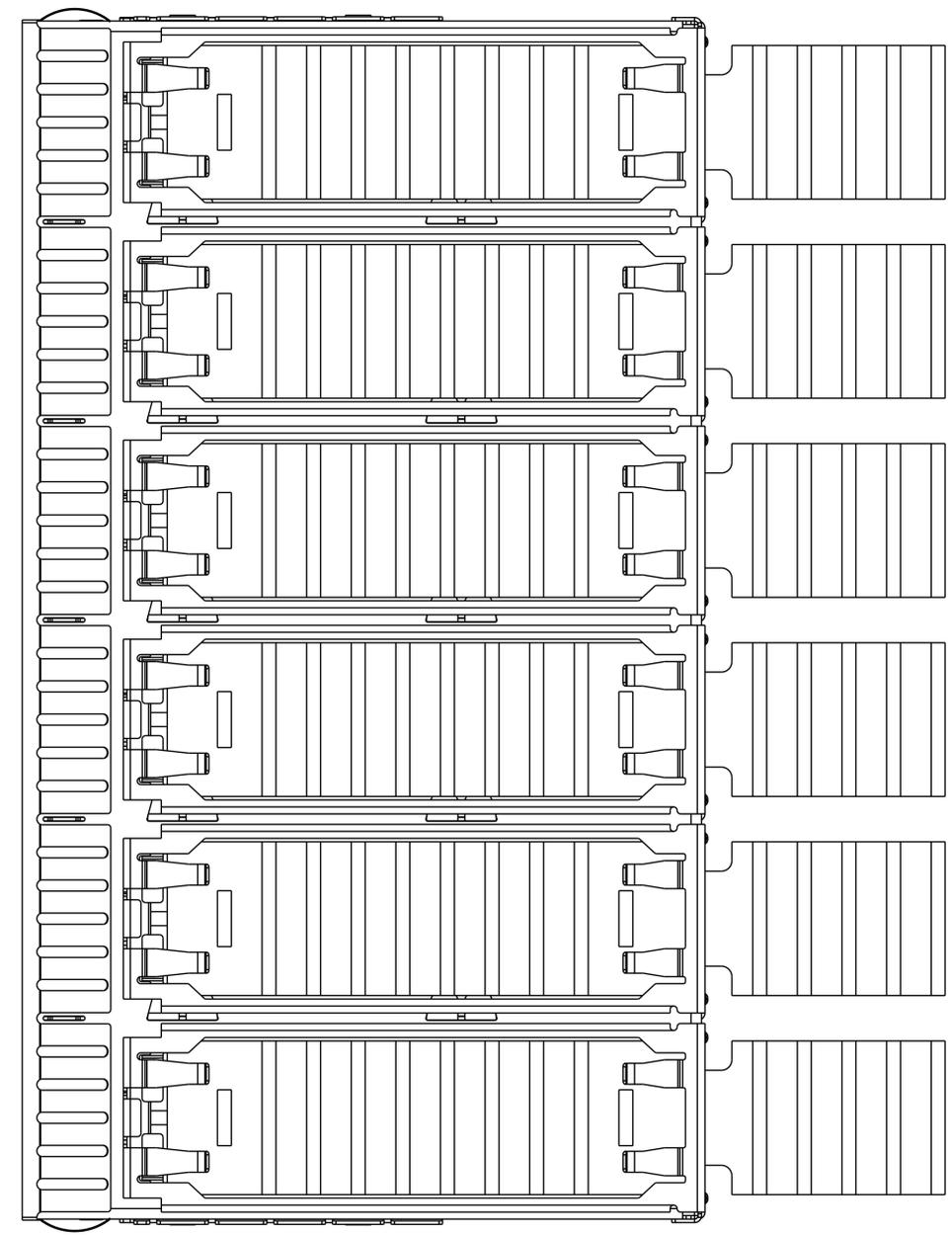
2170192-1 AS SHOWN
HEAT SINK W/O THE FIRST ROW PIN



2170192-2 AS SHOWN



2170192-3 AS SHOWN

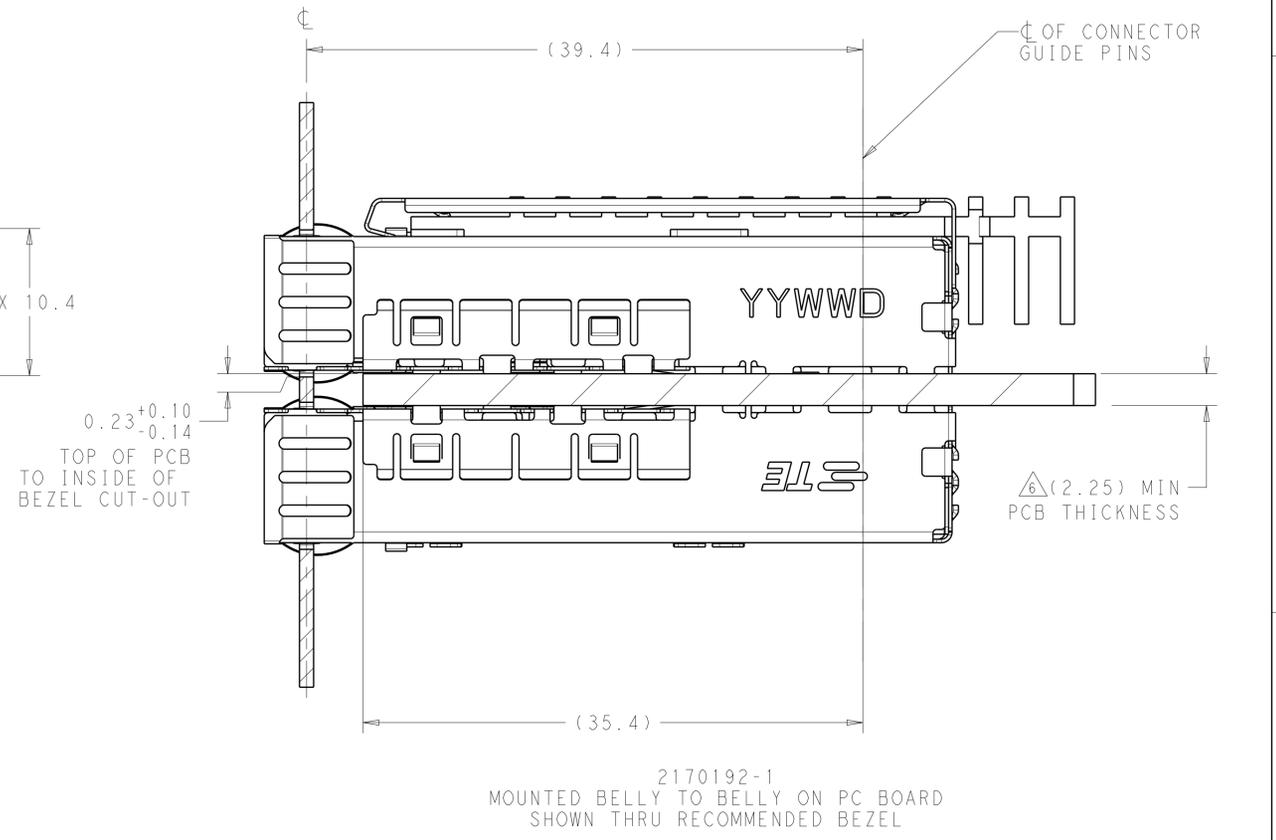
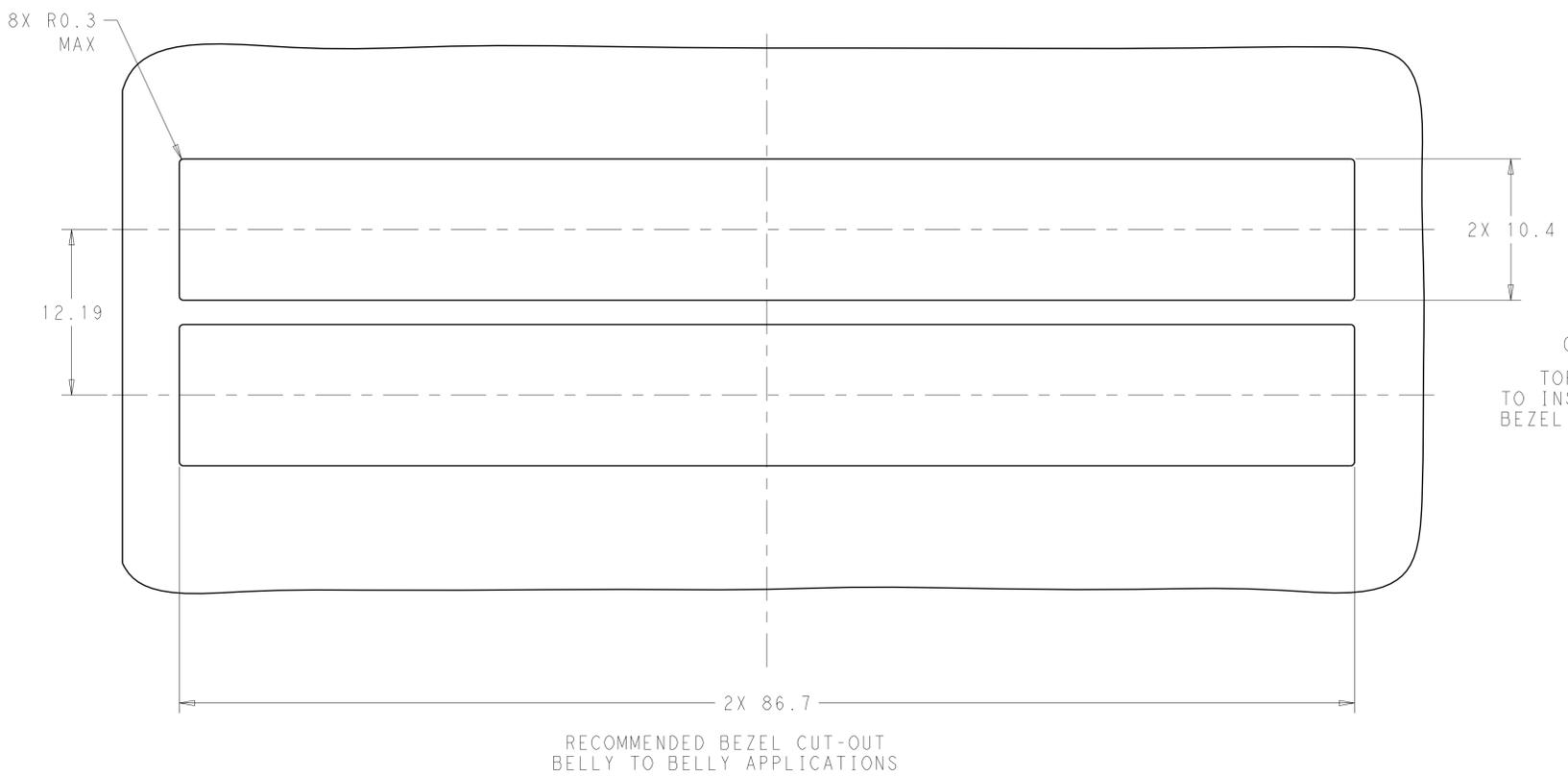
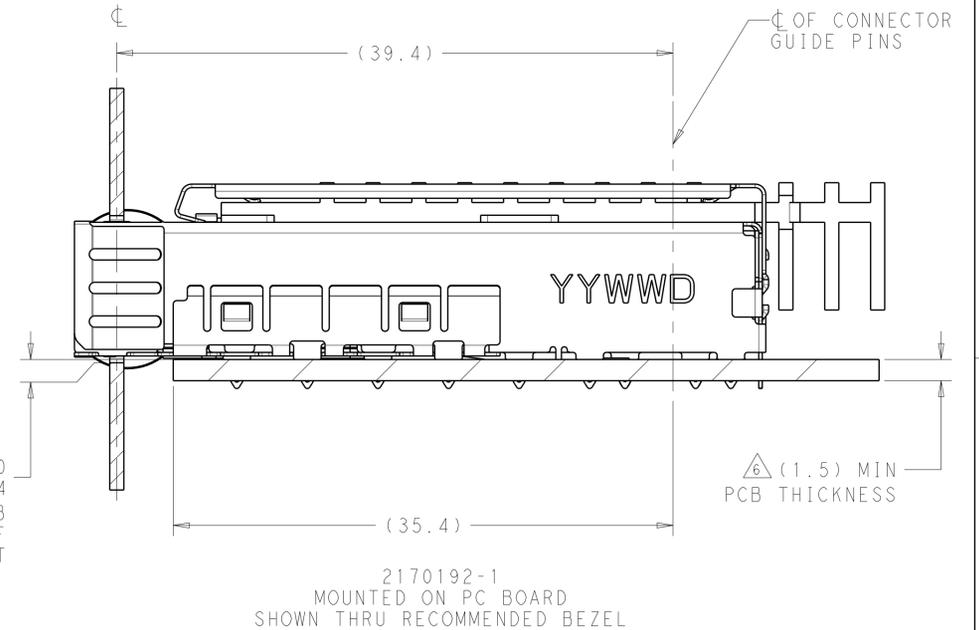
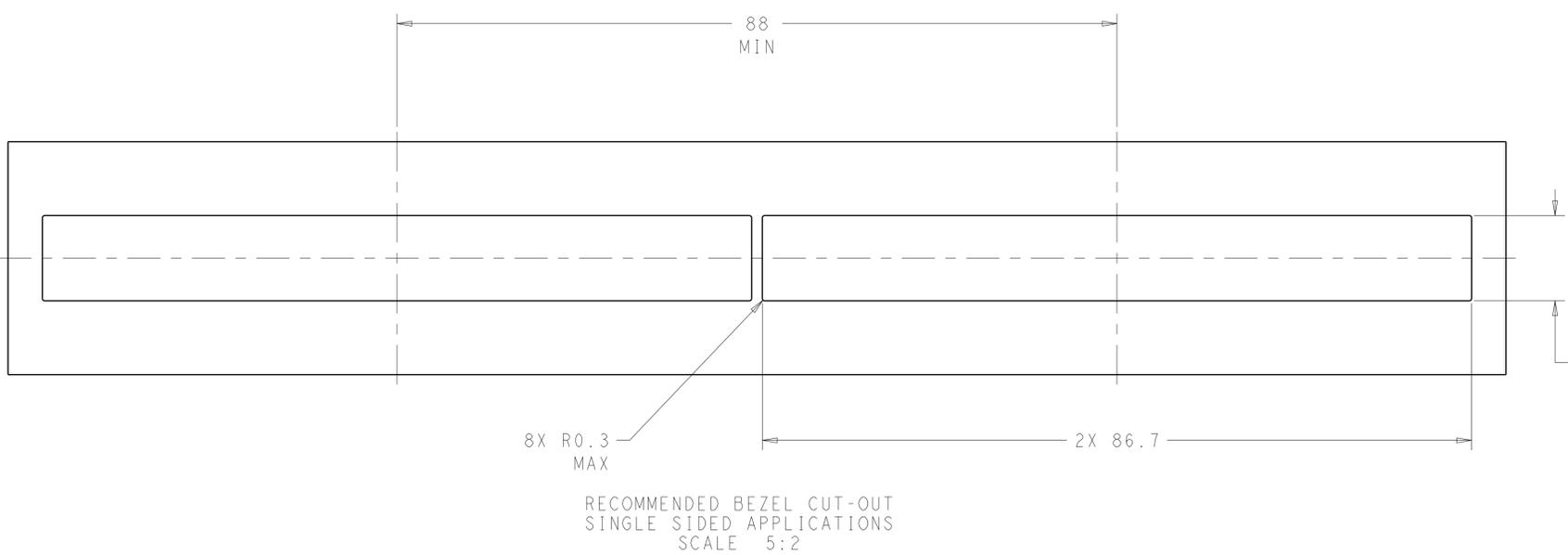


2170192-3 AS SHOWN

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DIMENSIONS:		CHK: ALEX CAI 22NOV2011	
mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD: ALEX CAI 22NOV2011	NAME: SFP+ ENHANCED 1X6 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK
	0 PLC ±0.25	PRODUCT SPEC: 108-2364	
	1 PLC ±0.20	APPLICATION SPEC: 114-13120	SIZE: CAGE CODE DRAWING NO. RESTRICTED TO
	2 PLC ±0.15	WEIGHT: -	A100779C=2170192
	3 PLC ±0.1	Customer Drawing	SCALE: 4:1 SHEET 2 OF 5 REV A
	4 PLC ±0.1		
	ANGLES ±1°		
MATERIAL:	FINISH:		

LOC	DIST	REV	DATE	BY	APPD
GP	00				

REVISIONS		DATE	BY	APPD
1	SEE SHEET 1			



THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: TIM XUE 22NOV2011	STE TE Connectivity
DIMENSIONS: mm		CHK: ALEX CAI 22NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: ALEX CAI 22NOV2011	NAME: SFP+ ENHANCED 1X6 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK
0 PLC ±0.25		PRODUCT SPEC: 108-2364	
1 PLC ±0.20		APPLICATION SPEC: 114-13120	SIZE: A100779C=2170192
2 PLC ±0.15		WEIGHT: -	
3 PLC ±0.1		Customer Drawing	SCALE: 4:1
4 PLC ±0.1			SHEET: 3 OF 5
ANGLES ±0.1			REV: A
FINISH: #1*			

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

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moschip.ru_9